

**Topical Workshop on Electronics
for Particle Physics
TWEPP 2024**

Oral Presentation Award

**3D Integration of Pixel Readout Chips
using Through-Silicon-Vias**

Presenter: Francisco Piernas Diaz¹

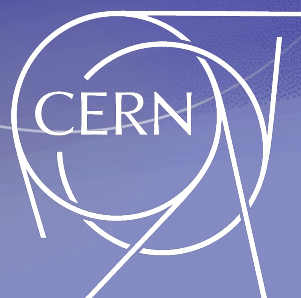
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